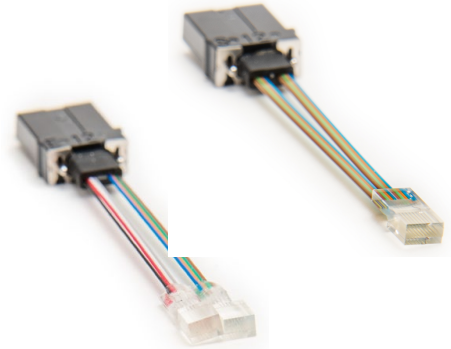


CORNING

At ECOC 2022, Corning is participating in a demonstration showcasing OIF work on Co-Packaged Optics Interoperability.

For this demo, Corning Inc has provided a mock-up of a fiber array unit (FAU) shown within the envelope of the OIF 3.2 Tbps CPO module where it couples with the SiP* O/E**. The realization represented here is an FR4*** scheme with a 16-channel FAU carrying 8 Tx and 8 Rx fibers alongside an 8-channel FAU with 8 aligned PM fibers bringing optical power to the chip from external laser sources.



Corning OEM offers a broad range of highly customizable Fiber Array Unit (FAU) assemblies for telecom, data center, and high performance computing applications. Corning's V-groove chip assemblies along with its capability of develop and produce specialty fibers enable Corning to meet a wide variety of challenging OEM requirements including inter-fiber core pitch precision, high channel counts and density, as well as different fiber and termination types. All our FAUs feature ultra-accurate fiber core position resulting in low insertion loss and high optical return loss, guaranteed by our state-of-the-art equipment and processes. As one of the innovators in materials science, Corning is also developing advanced fiber-to-chip connectivity solutions, such as integrated glass substrates, for meeting the needs of higher density and performance from your evolving photonic integrated circuit (PIC) requirements.

For more information Visit us at Booth #201 or at www.corning.com/worldwide/en/markets/Optical-communications-Market.html

*SiP - System in a Package

**O/E - Opto-Electronic

***FR4 - IEEE 802.3 - 100G x 4, SMF @ 2000km

